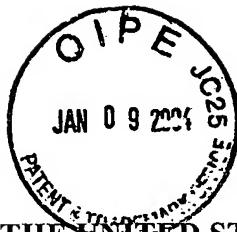


MICRON.133DV1



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

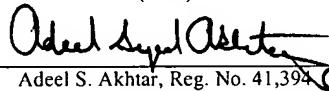
Applicant : Trivedi et al.  
Appl. No. : 10/038,305  
Filed : January 2, 2002  
For : METHOD OF FORMING A  
DUAL DAMASCENE  
INTERCONNECT BY  
SELECTIVE METAL  
DEPOSITION (As Amended  
Herewith)  
Examiner : Thanh T. Nguyen  
Group Art Unit : 2813

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

January 6, 2004

(Date)

  
Adeel S. Akhtar, Reg. No. 41,394

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JAN 14 2004  
TECHNOLOGY CENTER 2800

AMENDMENT AND RESPONSE TO OFFICE ACTION

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed October 7, 2003 in the above-identified application, Applicants respectfully request full consideration of the remarks contained herein.

**Amendments to the Specification** begin on page 2 of this paper.

**A listing of the claims** begins on page 3 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.